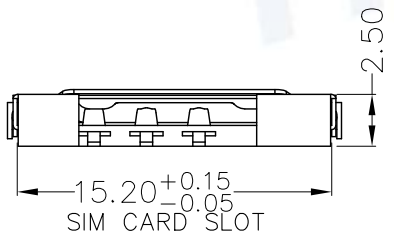
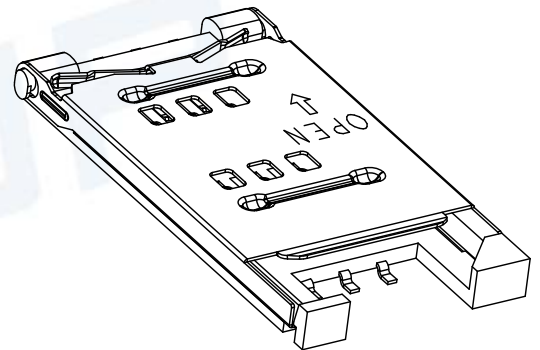
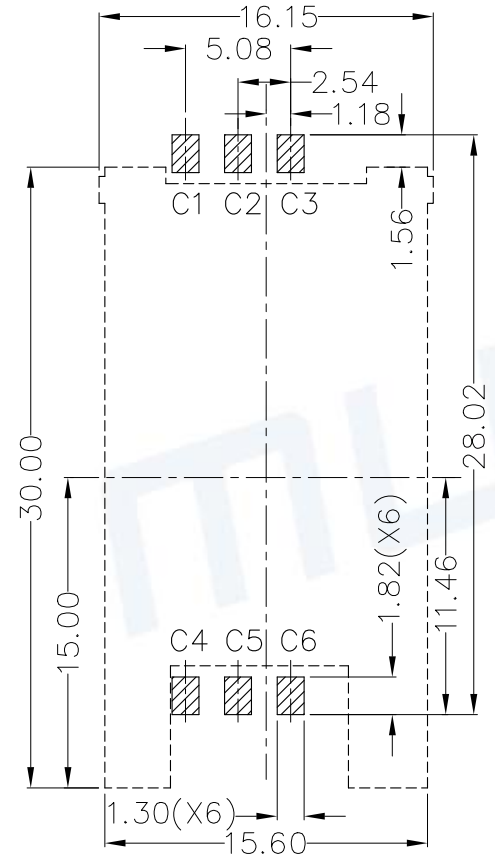
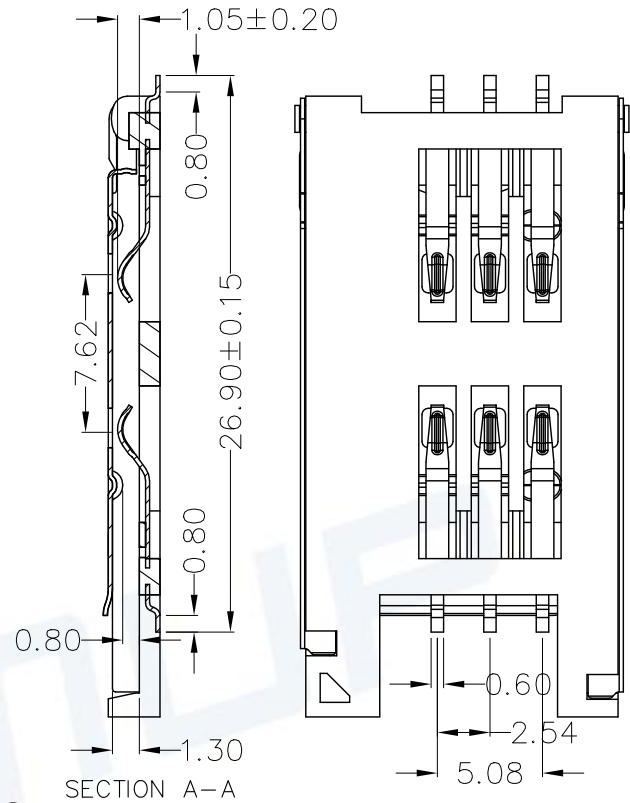
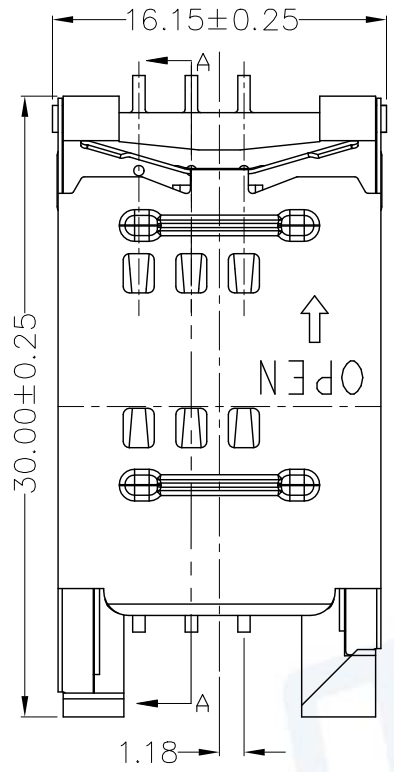


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



**TECHNICAL CHARACTERISTICS**

1.General Characteristics  
 Dimensions: 30.00LX16.15WX2.50H mm  
 Weight: Approx 1.30±0.2g  
 Durability: 5,000 cycles min.

2.Electrical Characteristics  
 Contact resistance: 50mΩ typical, 100mΩ max  
 Insulation resistance: >1000MΩ/500V DC

3.Solderability  
 Vapor phase: 215°C, 30sec. Max  
 IR reflow: 250°C, 5sec. Max  
 Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics  
 Operating temperature: -40°C~+85°C  
 Operating humidity: 10%~+95%RH

RECOMMENDED P.C.B LAYOUT  
 COMPONENT SIDE (TOLERANCE ±0.05)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Stainless steel	
3	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated

Unless otherwise specified, other tolerance are:

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C714-2**

TYPE: **H2.7 without post 6p**

PROJ.	UNIT	SCALE	DRAWN	Zoey Apr.09.2009	DWG NO.:	DWG-MUP-C714-002
	mm	1:1	CHECKED	Jimmy Apr.09.2009	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Simon Apr.09.2009	REVISION	X1

